

Product Name: SSM6P816R

Package Name: TSOP6F

1. Thermal tests

Test Item	Test Condition	Failure Size / Sample Size
Heat resistance (Reflow)	Peak : 260 deg.C(a moment) Reflow zone : 230 deg.C 30 to 50 s Preheat : 180 to 190 deg.C , 60 to 120 s 4 times	0 / 32
Heat resistance (Flow)	Peak : 260 deg.C Immersion time : 10 s Once	0 / 32
Heat resistance (Iron)	Temperature of the iron tip : 400 deg.C Time : 3 s Once	0 / 32
Temperature cycling	- 55 deg.C(30 min) to 150 deg.C(30 min) ,100 cycles	0 / 50

2. Mechanical tests

Test Item	Test Condition	Failure Size / Sample Size
Solderability	Solder bath : Sn-Ag-Cu 245 deg.C , 5 s ,once (using Flux) Solder bath : Sn-Pb 230 deg.C , 5 s ,once (using Flux)	0 / 11
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-	-	-
-	-	-
-	-	-

3. Life tests

Test Item	Test Condition	Failure Size / Sample Size
Steady state operation	Ta = 25 deg.C, PD = 1.4W ,1000 h	0 / 30
High temp. reverse bias	Ta = 150 deg.C, VGS = -10V ,1000 h	0 / 30
High temp. storage	Ta = 150 deg.C ,1000 h	0 / 30
High temp. high humidity storage	Ta = 85 deg.C, RH = 85% ,1000 h	0 / 30
Pressure cooker test	Ta = 121 deg.C(203kPa)(Unsaturated) ,96 h	0 / 20
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For detailed reliability test information, such as test conditions and criteria, please contact your Toshiba sales representative.

Product Name: SSM6P816R

Package Name: TSOP6F

1.Reflow

Number: 4 times maximum

Peak : 260 deg.C(a moment)

Reflow zone : 230 deg.C 30 to 50 seconds

Preheat : 180 to 190 deg.C , 60 to 120 seconds

NOTE: Heat resistant condition are based on the device surface temperature.

An example of a temperature profile is shown in Fig.1.

This profile has indicated the maximum of a device heat-resistance guarantee.

Please set preheating temperature / heating temperature as the best temperature according to the kind of solder paste to use, within the limits of Fig.1.

For the packages allowing mounting twice or more, the mounting should be completed with the interval from the first to the last mounting being within 2 weeks.



Fig.1 Example of Heat-resistant Temperature Profile

2.Others

We urge you to verify well before mounting to assure enough solder joint strength.

Always solder the Product in accordance with the heat-resistance mounting conditions set forth above. In the event the Product is soldered otherwise, the applicable product warranty, if any, is void.

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